

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Change boilerplate to add device class V. Add case outline H for vendor CAGE 24355. Editorial changes throughout.	97-05-30	R. MONNIN

THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.

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REV STATUS OF SHEETS	REV																			
	SHEET	1	2	3	4	5	6	7	8	9	10	11								

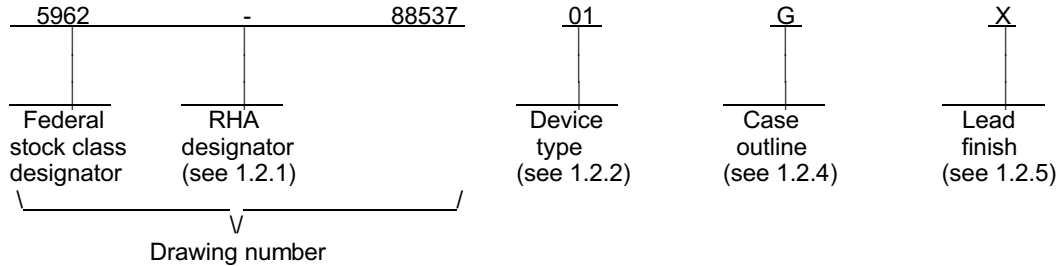
<p>PMIC N/A</p> <p>STANDARD MICROCIRCUIT DRAWING</p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p>AMSC N/A</p>	<p>PREPARED BY Rajesh Pithadia</p>	<p>DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216</p>																	
	<p>CHECKED BY Rajesh Pithadia</p>																		
	<p>APPROVED BY Raymond Monnin</p>	<p>MICROCIRCUIT, LINEAR, LOW-NOISE, PRECISION, HIGH SPEED OPERATIONAL AMPLIFIER, MONOLITHIC SILICON</p>																	
	<p>DRAWING APPROVAL DATE 88-10-17</p>																		
	<p>REVISION LEVEL A</p>																		
<p>SHEET 1 OF 11</p>																			

1. SCOPE

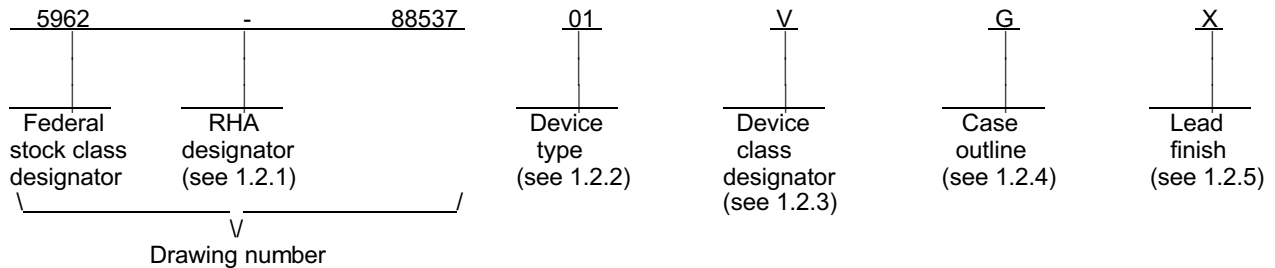
1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following examples.

For device classes M and Q:



For device class V:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	OP-37A	Low-noise, precision, high-speed operational amplifier
02	OP-37B	Low-noise, precision, high-speed operational amplifier
03	OP-37C	Low-noise, precision, high-speed operational amplifier

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 2

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
G	MACY1-X8	8	Can
H	GDFP1-F10 or CDFP2-F10	10	Flat pack
P	GDIP1-T8 or CDIP2-T8	8	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings 1/

Supply voltage (V_S)	-----	± 22 V
Internal power dissipation 2/	-----	500 mW
Input voltage 3/	-----	± 22 V
Output short-circuit duration	-----	Indefinite
Differential input voltage 4/	-----	± 0.7 V
Differential input current 4/	-----	± 25 mA
Storage temperature range	-----	-65°C to $+150^\circ\text{C}$
Operating temperature range	-----	-55°C to $+125^\circ\text{C}$
Lead temperature (soldering, 60 seconds)	-----	$+300^\circ\text{C}$
Junction temperature range (T_J)	-----	-65°C to $+150^\circ\text{C}$
Thermal resistance, junction-to-case (θ_{JC})	-----	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θ_{JA}):		
Cases G and H	-----	150 $^\circ\text{C/W}$
Case P	-----	119 $^\circ\text{C/W}$
Case 2	-----	110 $^\circ\text{C/W}$

1.4 Recommended operating conditions.

Supply voltage (V_S)	-----	± 15 V
Source resistor (R_S)	-----	50 Ω
Ambient operating temperature range (T_A)	-----	-55°C to $+125^\circ\text{C}$

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

MILITARY

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

- 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- 2/ Must withstand the added P_D due to short circuit test, e.g., I_{OS} .
- 3/ For supply voltages less than ± 22 V, the absolute maximum input voltage is equal to the supply voltages.
- 4/ The device inputs are protected by back-to-back diodes. Current limiting resistors are not used in order to achieve low noise. If differential input voltage exceeds ± 0.7 V, the input current should be limited to 25 mA.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 3

STANDARDS

MILITARY

- MIL-STD-883 - Test Methods and Procedures for Microelectronics.
- MIL-STD-973 - Configuration Management.
- MIL-STD-1835 - Microcircuit Case Outlines.

HANDBOOKS

MILITARY

- MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).
- MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 4

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Input offset current	I _{IO}		1	01		35	nA
			2, 3			50	
			1	02		50	
			2, 3			85	
			1	03		75	
			2, 3			135	
Average input bias current	I _B		1	01		±40	nA
			2, 3			±60	
			1	02		±55	
			2, 3			±95	
			1	03		±80	
			2, 3			±150	
Common-mode rejection ratio	CMRR	V _{CM} = IVR = ±11 V <u>2/</u>	1	01	114		dB
		V _{CM} = IVR = ±10 V <u>2/</u>	2, 3		108		
		V _{CM} = IVR = ±11 V <u>2/</u>	1	02	106		
		V _{CM} = IVR = ±10 V <u>2/</u>	2, 3		100		
		V _{CM} = IVR = ±11 V <u>2/</u>	1	03	100		
		V _{CM} = IVR = ±10 V <u>2/</u>	2, 3		94		
Power supply rejection ratio	PSRR	V _S = ±4.5 V to ±18 V	1	01		10	μV/V
			2, 3			16	
			1	02		10	
			2, 3			20	
			1	03		20	
			2, 3			51	

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 5

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions ^{1/} -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Large-signal voltage gain	A _{VO}	V _O = ±10 V, R _L ≥ 2 kΩ	1	01	1000		V/mV
			2, 3		600		
			1	02	1000		
			2, 3		500		
			1	03	700		
			2, 3		300		
Output voltage swing	V _O	R _L ≥ 2 kΩ	1	01	±12		V
			2, 3		±11.5		
			1	02	±12		
			2, 3		±11.0		
			1	03	±11.5		
			2, 3		±10.5		
Power dissipation	P _D	No load, T _A = +25°C	1	01, 02		140	mW
				03		170	
Offset voltage adjustment range	V _{OSADJ}	R _P = 10 kΩ, T _A = +25°C ^{3/}	1	All	±0.5		mV
Supply current	I _S	No load, T _A = +25°C	1	01, 02		4.67	mA
				03		5.67	
Output short-circuit current	I _{OS} ⁺	T _A = +25°C	1	All		80	mA
	I _{OS} ⁻					-80	
Input offset voltage	V _{IO}		4	01		25	μV
			5, 6			60	
			4	02		60	
			5, 6			200	
			4	03		100	
			5, 6			300	

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 6

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions ^{1/} -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Slew rate	SR	V _O = ±7.5 V, R _L = 2 kΩ C _L = 50 pF, T _A = +25°C	7	All	11		V/μs
Average input offset voltage drift	TCV _{OS}	Unnullled ^{4/} T _A = -55°C, +125°C	8	01		0.6	μV/°C
				02		1.3	
				03		1.8	

^{1/} V_S = ±15 V, R_S = 50 Ω, unless otherwise specified.

^{2/} IVR is defined as the V_{CM} range used for the CMRR test.

^{3/} R_P is a trim potentiometer used for adjustment of V_{OS}.

^{4/} TCV_{OS} is guaranteed, if not tested, to the limits specified.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.

3.9 Verification and review for device class M. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 7

Device types	01, 02, 03		
Case outlines	G, P	H	2
Terminal number	Terminal symbol		
1	V_{OS} Trm	NC	NC
2	-IN	NULL	V_{OS} Trm
3	+IN	-IN	NC
4	V_S	+IN	NC
5	NC	V_S	-IN
6	OUT	NC	NC
7	V_{S+}	OUT	+IN
8	V_{OS} Trm	V_{S+}	NC
9	----	NULL	NC
10	----	NC	V_S
11	----	----	NC
12	----	----	NC
13	----	----	NC
14	----	----	NC
15	----	----	OUT
16	----	----	NC
17	----	----	V_{S+}
18	----	----	NC
19	----	----	NC
20	----	----	V_{OS} Trm

NC = No connection

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 8

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.

(2) $T_A = +125^\circ\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table IIA herein.

4.2.2 Additional criteria for device classes Q and V.

a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

b. Interim and final electrical test parameters shall be as specified in table IIA herein.

c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

a. Tests shall be as specified in table IIA herein.

b. Subgroups 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 9

TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1, 2, 3, 4, 5, 6 1/	1,2,3,4,5,6 1/	1,2,3,4,5,6 1/ 2/
Group A test requirements (see 4.4)	1,2,3,4,5,6,7,8	1,2,3,4,5,6,7,8	1, 2, 3, 4, 5, 6, 7, 8
Group C end-point electrical parameters (see 4.4)	1	1	1 2/
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	----	----	----

1/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous interim electrical parameters.

TABLE IIB. 240 hour burn-in and group C end-point electrical parameters.

Test	Limit		Delta		Unit
	Min	Max	Min	Max	
V _{OS}		100		75	μV
I _B		40		8	nA
I _{OS}		35		7	nA

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
- b. T_A = +125°C, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 10

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^\circ\text{C} \pm 5^\circ\text{C}$, after exposure, to the subgroups specified in table IIA herein.
- c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.

6.4 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0674.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216	SIZE A		5962-88537
		REVISION LEVEL B	SHEET 11

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 97-05-30

Approved sources of supply for SMD 5962-88537 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /	Equivalent device specification part number
5962-8853701VGA	24355	OP37AJ/QMLV	----
5962-8853701GA	07933 24355 64155	OP-37AT/883B OP-37AJ/883 OP-37AH/883	M38510/13505BGX
5962-8853701GC	07933	OP-37AT/883B	M38510/13505BGX
5962-8853701VPA	24355	OP37AZ/QMLV	----
5962-8853701PA	07933 24355 64155	OP-37AD/883B OP-37AZ/883 OP-37AJ8/883	M38510/13505BPX
5962-8853701V2A	24355	OP37ARC/QMLV	----
5962-8853701VHA	24355	OP37AL/QMLV	----
5962-88537012A	<u>3</u> /	OP-37AL/883	M38510/13505B2X
5962-88537022A	24355	OP-37BRC/883	M38510/13505B2X
5962-8853702GA	07933 24355	OP-37BT/883B OP-37BJ/883	M38510/13505BGX
5962-8853702GC	07933	OP-37BT/883B	M38510/13505BGX
5962-8853702PA	07933 24355	OP-37BD/883B OP-37BZ/883	M38510/13505BPX

See footnotes at end of table

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.

STANDARD MICROCIRCUIT DRAWING BULLETIN - Continued

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>	Equivalent device specification part number
5962-8853703GA	07933 24355 64155	OP-37CT/883B OP-37CJ/883 OP-37CH/883	M38510/13505BGX
5962-8853703GC	07933	OP-37CT/883B	M38510/13505BGX
5962-8853703PA	07933 64155	OP-37CD/883B OP-37CJ8/883	M38510/13505BPX
5962-88537032X	<u>3/</u>	OP-37CL/883	M38510/13505B2X

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. The device manufacturers listed herein are authorized to supply alternate lead finishes "A", "B", or "C" at their discretion. Contact the listed approved source of supply for further information.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

3/ Not available from an approved source of supply.

Vendor CAGE
number

Vendor name
and address

24355

Analog Devices
RT 1 Industrial Park
PO Box 9106
Norwood, MA 02062
Point of contact: 1500 Space Park Drive
PO Box 58020
Santa Clara, CA 95052-8020

64155

Linear Technology Corporation
1630 McCarthy Boulevard
Milpitas, CA 95035-7487

07933

Raytheon Company
Semiconductor Division
350 Ellis Street
Mountain View, CA 94039-7016